

Semiconductor Assembly and Packaging Services Market 2019 Global Analysis, Opportunities and Forecast to 2025

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Semiconductor Assembly and Packaging Services Market 2019

Semiconductor assembly and packaging services are crucial in the semiconductor production process. The package of the semiconductor device is usually made of materials such as plastic, metal, and ceramic/glass. Packaging is undertaken to provide protection against impact and corrosion.

The communication sector accounted for the largest share of the semiconductor assembly and packaging services market during 2017. According to Technavio's market research analysts, this segment is likely to continue its dominance in the wafer fabrication market throughout the forecast period.

APAC accounted for the largest share of the semiconductor assembly and packaging services market during 2017. According to research analysts, this regional segment is likely to continue its dominance in the wafer fabrication market throughout the forecast period.

In 2018, the global Semiconductor Assembly and Packaging Services market size was xx million US\$ and it is expected to reach xx million US\$ by the end of 2025, with a CAGR of xx% during 2019-2025.

This report focuses on the global Semiconductor Assembly and Packaging Services status, future forecast, growth opportunity, key market and key players. The study objectives are to present the Semiconductor Assembly and Packaging Services development in United States, Europe and China.

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The key players covered in this study
Advanced Semiconductor Engineering (ASE)

Amkor Technology
Intel
Samsung Electronics
SPIL
TSMC
...

Market segment by Type, the product can be split into
Assembly Services
Packaging Services

Market segment by Application, split into
Telecommunications
Automotive
Aerospace and Defense
Medical Devices
Consumer Electronics
Other

Market segment by Regions/Countries, this report covers
United States
Europe
China
Japan
Southeast Asia
India
Central & South America

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